

Bill of Materials

TI DESIGNS

TIPD126: Bridge Sensor Signal Conditioner with Current Loop, EMC Compatibility

Item #	Quantity	Value	Designator	Description	Manufacturer	Part Number	Supplier Part Number 1
1	4	100nF	C1, C2, C6, C12	CAP CER 0.1UF 10V 10% X7R 0402	TDK Corporation	C1005X7R1A104K050BB	445-4958-1-ND
2	2	100pF	C3, C4,	CAP CER 100PF 50V 10% X7R 0402	Yageo	CC0402KRX7R9BB101	311-1419-1-ND
3	4	10nF	C5, C7, C9, C10	CAP CER 10000PF 10V 10% X7R 0402	Kemet	C0402C103K8RACTU	399-7759-1-ND
4	1	10nF	C8	CAP CER 10000PF 50V 10% X7R 0603	TDK Corporation	C1608X7R1H103K080AA	445-1311-1-ND
5	1	1nF	C11	CAP CER 1000PF 6.3V 10% X7R 0402	Kemet	C0402C102K9RACTU	399-8941-1-ND
6	2	39.2K	R1, R6	RES 39.2K OHM 1/10W 1% 0402 SMD	Panasonic Electronic Components	ERJ-2RKF3922X	P39.2KLCT-ND
7	1	191K	R2	RES 191K OHM 1/10W 1% 0402 SMD	Panasonic Electronic Components	ERJ-2RKF1913X	P191KLCT-ND
8	1	100	R3	RES 100 OHM 1/10W 1% 0402 SMD	Panasonic Electronic Components	ERJ-2RKF1000X	P100LCT-ND
9	1	11.3K	R4	RES 11.3K OHM 1/16W 0.1% 0402	TE Connectivity	4-1879215-1	A102592CT-ND
10	1	10K	R5	RES 10.0K OHM 1/16W 0.1% 0402	TE Connectivity	7-1879208-3	A102579CT-ND
11	1	0	R7	RES 0.0 OHM 1/10W 0402 SMD	Panasonic Electronic Components	ERJ-2GE0R00X	PO.OJCT-ND
12	1	N/A	R8	DNP, 0402	N/A	N/A	N/A
13	2	4.7K	R9, R10	RES 4.70K OHM 1/10W 1% 0402 SMD	Panasonic Electronic Components	ERJ-2RKF4701X	P4.70KLCT-ND
14	2	FERRITE BEAD	FB1, FB2	FERRITE 300MA 600 OHM 0603 SMD	Laird-Signal Integrity Products	HZ0603C601R-10	240-2380-1-ND
15	1	TVS	D1	TVS BIDIRECT 600W 5V SMB	Fairchild Semiconductor	SMBJ5V0CA	SMBJ5V0CACT-ND
16	1	SCHOTTKY	D2	DIODE SCHOTTKY 70V 70MA SOT23	Micro Commercial Co	BAS70-TP	BAS70TPMSCT-ND
17	1	TVS	D3	TVS BIDIRECT 600W 40V SMB	Fairchild Semiconductor	SMBJ40CA	SMBJ40CAFSCT-ND
18	1	NPN	Q1	TRANSISTOR NPN 45V 2000MA SOT-89	Diodes Inc	FCX690BTA	FCX690BCT-ND
19	1	XTR117	U1	XTR117	Texas Instruments	XTR117AIDGKT	296-18744-1-ND
20	1	PGA309	U2	PGA309	Texas Instruments	PGA309AIPWR	296-16726-1-ND
21	1	EEPROM	U3	IC EEPROM 16KBIT 400KHZ SOT23-5	Microchip Technology	24LC16BHT-I/OT	24LC16BHT-I/OTCT-ND
22	2		J1, J3	CONN HEADER 2POS .100" T/H GOLD	Samtec Inc	HTSW-102-07-G-S	HTSW-102-07-G-S-ND
23	1		J2	CONN HEADER 5POS .100" T/H GLD	Samtec Inc	HTSW-105-07-G-S	HTSW-105-07-G-S-ND

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